

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO.

990559

SERIAL NO.

09/320,271

LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

APPLICANT

WATANABE et al.

FILING DATE

May 27, 1999

GROUP

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EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
CL	AA	5,024,723	06/18/91	Goesele, et al.	156	628	
	AB	5,616,513	04/01/97	Shepard	438	402	
	AC	5,674,784	10/07/97	Jang, et al.	437	195	
	AD	5,723,895	03/03/98	Takahashi	257	499	
	AE	5,830,773	11/03/98	Brennan, et al.	437	67	
	AF	5,581,101	12/3/96	Ning et al.	257	347	
	AG	4,962,052	10/09/90	Asayama, et al.	437	31	
	AH	5,930,624	07/27/99	Murata, et al.	438	253	
	AI	5,153,680	10/06/92	Naito, et al.	438	687	
	AJ	3,747,203	07/24/73	Shannon	438	629	
	AK	5,166,768	11/24/92	Ito	438	637	
	AL	4,676,867	06/30/87	Elkins, et al.	156	643	
	AM	4,775,550	10/04/88	Chu, et al.	427	38	
	AN	4,885,262	12/05/89	Ting, et al.	437	231	
	AO	4,983,546	01/08/91	Hyun, et al.	437	231	
	AP	5,003,062	03/26/91	Yen	437	231	
	AQ	5,106,787	04/21/92	Yen	437	231	
	AR	5,352,630	10/04/94	Kim, et al.	437	195	
	AS	5,549,786	08/27/96	Jones, et al.	156	662.1	
	AT	4,984,055	01/1991	Okumura, et al.	257	644	
	AU	5,270,259	12/1993	Ito, et al.	437	235	
	AV	5,468,684	11/1995	Yoshimori,, et al.	437	228	
	AW	5,087,589	02/11/92	Chapman, et al.	437	195	
	AX	5,963,827	10/1999	Enomoto et al.	438	629	
	AY	5,341,026	08/23/94	Harada, et al.	257	764	
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<u>CL</u>	AA	5,404,046	Matsumoto, et al.	04/95	257	750
<u>CL</u>	AB	5,786,273	Hibi, et al.	07/98	438	637
<u>CL</u>	AC	5,892,269	Inoue, et al.	04/99	257	634
<u> </u>	AD					
<u> </u>	AE					
<u> </u>	AF					

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Document No.	Date	Country	Translation (Yes or No)
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<u> </u> AM	

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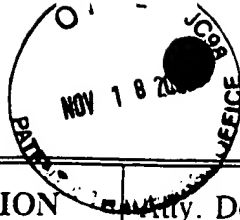
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CL	BA	5,607,880	03/04/97	Suzuki	437	195	
	BB	5,702,568	12/30/97	Shin, et al.	156	644	
	BC	5,314,834	08/26/91	Mazure, et al.	438	595	
	BD	5,866,476	02/02/99	Choi, et al.	438	624	
	BE	5,084,412	01/28/92	Nakasaki	437	189	
	BF	5,479,054	12/26/95	Tottori	257	752	
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	BI	5,817,582	10/06/98	Maniar	438	782	
	BJ	5,569,618	10/29/96	Matsubara	437	52	
	BK	5,186,745	02/16/93	Maniar	106	287	
	BL	5,496,776	03/05/96	Chien, et al.	437	231	
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	BP	JP 6-291202	10/18/94	Japan	Abstract	
	BQ	JP 63 198359	8/17/88	Japan	Abstract	
	BR	10-303295	11/13/98	Japan	Abstract	
	BS	59-017243	01/28/84	Japan	Abstract	
	BT	58-031519	02/24/83	Japan	Abstract	
	BU	10-209147	08/07/98	Japan	Abstract	
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	BW	09-330982	12/22/97	Japan	Abstract	
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	BY	01-199456	08/10/89	Japan	Abstract	
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INFORMATION DISCLOSURE STATEMENT PTO-1449	Applicant(s): WATANABE et al.	Serial No. 09/320,271
	Filing Date: May 27, 1999	Group Art Unit: 2825

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	AC	5,314,843	Yu, et al.	05/94		
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	AG	5,387,812	Forouhi, et al.	2/95		
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<u>CL</u>	AI	4,668,973	Dawson, et al.	5/87		
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<u>CL</u>	AL	0179563	11/27/98	Korea	Abstract
<u>CL</u>	AM	EP 0 602 607 A1	6/22/94	Europe	Yes
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	CC	02-026055	01/29/90	Japan	Abstract	
	CD	04-234149	08/21/92	Japan	Abstract	
	CE	07-099195	04/11/95	Japan	Abstract	
	CF	02-253643	10/12/90	Japan	Abstract	
	CG	02-007451	01/11/90	Japan	Abstract	
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	CI	06-275229	09/30/94	Japan	Abstract	
	CJ	05-198523	08/06/93	Japan	Abstract	
	CK	04-317358	11/09/92	Japan	Abstract	
	CL	08-064561	03/08/96	Japan	Abstract	
	CM	01-307247	12/12/89	Japan		No
	CN	JP 56-125844	10/2/81	Japan	Abstract	
	CO	02-101532	08/13/90	Japan	Yes	
	CP	02-235358	09/18/90	Japan	Yes	
	CQ	04-307934A	10/30/92	Japan		No
CL	CR	DE 42 18 495	12/10/92	Germany		No

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CL	CS	"Multilevel-Interconnection Technology for VLSI and ULSI," Silicon Processing for the VLSI Era - Volume II, (pp. 232-233).
CL	CT	"Lithography I: Optical Resist Material and Process Technology," (pp. 441).
CL	CU	1995 Proceedings 12th International VLSI Multilevel Interconnection Conference (VMIC Catalog No. 95ISMIC - 104), June 27-29, 1995.
CL	CV	Wang, et al., "A Study of Plasma Treatments on Siloxane SOB," IEEE VMIC Conference, June 7-8, 1994, pp. 101-107.
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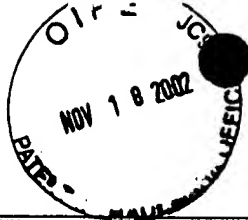
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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<u>CL</u>	AR	Wolf et al."Silicon Processing for the VLSI Era: Volume I - Process Technology," "Lattice Press, 1986 p. 441
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<u>CL</u>	AV	Office Action of Japanese Application No. 08-345587.
<u>CL</u>	AW	Office Action Of Japanese Application No. 09-012788.
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Related Copending Applications

<u>Application No.</u>	<u>Filing Date</u>	<u>Attorney Docket No.</u>	<u>Status</u>
08/921,250	8/29/97	970813	Pending
08/806,425	2/26/97	970150	5,892,269 (Issued)
09/228,148	1/11/99	970150A	Pending
09/160,044	09/25/98	981187	6,235,648 (Issued)
09/716,334	11/21/00	981187A	Pending
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